



Material Content Data Sheet



Sales Product Name		IPD35N10S3L-26		Issued		2. August 2018		
MA#		MA001795130						
Package		PG-TO252-3-11		Weight*		371.40 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.025	0.81	0.81	8146	8146
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	iron	7439-89-6	0.215	0.06		580	
	non noble metal	copper	7440-50-8	215.017	57.89	57.97	578931	579685
	non noble metal	aluminium	7429-90-5	2.495	0.67	0.67	6718	6718
wire	non noble metal	aluminium	7429-90-5	2.495	0.67	0.67	6718	6718
encapsulation	organic material	carbon black	1333-86-4	1.244	0.34		3350	
	plastics	epoxy resin	-	21.772	5.86		58621	
	inorganic material	silicondioxide	60676-86-0	101.395	27.30	33.50	273006	334977
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10070	10070
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	244	245
solder	non noble metal	tin	7440-31-5	0.063	0.02		169	
	noble metal	silver	7440-22-4	0.079	0.02		211	
	non noble metal	lead	7439-92-1	2.999	0.81	0.85	8076	8456
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.16	5.17	51635	51703
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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